

ABSTRACT OF THE DISCLOSURE

sub
HX 7
A circuit board which ^{includes} ~~comprises~~ a conductive pattern
section 4 with a pattern formed on a conductive layer 3,
~~provided on a board main body 2, wherein two or more bonding~~
5 ~~positions 6a, 6b, 6c that bumps of a part mounted by~~
~~ultrasonic bonding strike are set in the conductive pattern~~
~~section 4,~~ characterized in that a notch part 8a, or a recess
extending from the margin of the conductive pattern section 4
to the inside thereof and reaching the proximity of ~~the a~~
10 bonding position, or an isolated notch part 8b ~~or recess~~ is
formed in the conductive layer ³ ~~1~~ in the proximity of ~~at least~~
a ~~one~~ bonding position ^{corresponding to the position of connection of}
a part by ultrasonic bonding.

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